Change List:

SCHEMATIC: [Up to date] PCB: All elements that have a pad, make sure that there is a pad pin and it's footprint is has the pad assigned to it Check that all components with a pad are connected with solder paste in footprint Add a cut out around temperature sensor (SHT35-D) Add vias to mounting holes for style Make logo in copper layer, not silkscreen How do I route a 90 ohm USB trace Put croptop sign in copper layer Move ADC over star ground Move memory and ADC to different busses Add heat sinks to motor drivers Ground plane on top and bottom layer Look into thermal vias for motor drivers Add silkscreen labels to configuration resistors When laying out the footprint for the motor drivers, follow datasheet Move micro usb and GPU connector further forward Add ground plane to top and bottom layers Stitch top and bottom layers together with vias SPI 12C and R5232 testpoints should be closer to pic, or at fork point Label Terminal blocks on top side Make test points bigger {--> R y a n t o l d y o u t o<--} Add a via fence and copper perimeter to board edge COMPLETION STEPS: Manually check entire board with Ryan, with each datasheet Calculate power rail burdens Figure out if ESD diodes will mess up ADC measurements Figure out of every chip and verify it's connection Verify the package footprint of every chip Make sure that 3V3 rotary encoder buffer resistor is DNP

List of Schematic Sheets

Microcontroller	Display
croptop_mcu.sch	croptop_lcd.sch
Onboard Peripherals	IO Peripherals
croptop_onboard.sch	croptop_io.sch

Kennedy Caisley, Ryan Donahue	
Iniversity of Idaho	
Sheet: /	
ile: croptop.sch	
Title: CropTop 2.0	
Size: USLetter Date: 2019-03-18	Rev: Revision 12
(iCad E.D.A. kicad (5.0.1)-3	ld: 1/5







